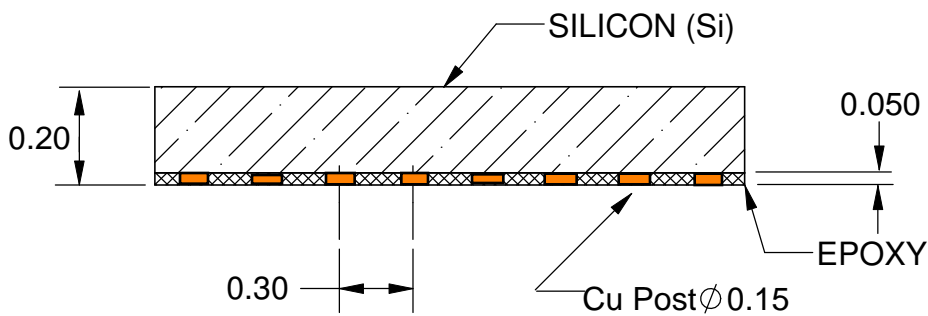
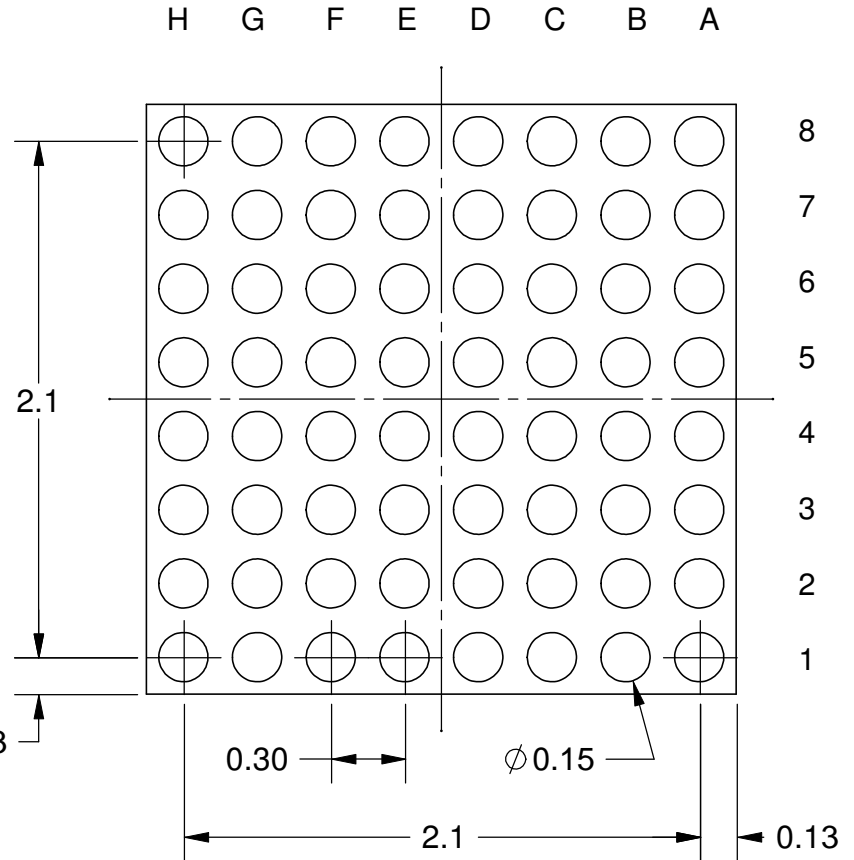
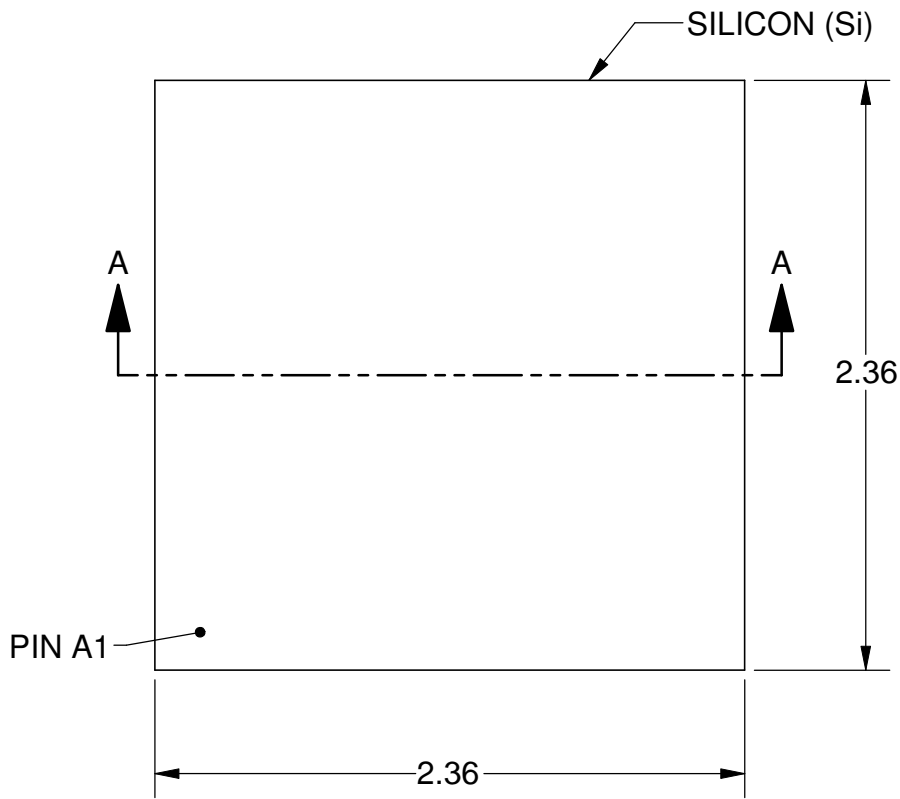


TOP VIEW

PAD VIEW



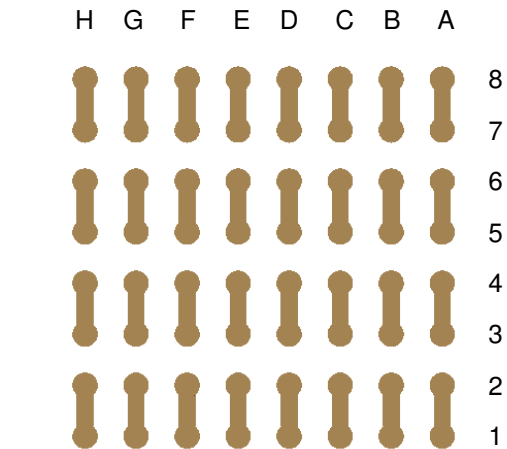
SECTION A-A

- Notes: (Unless Otherwise Specified).
 1) ALL DIMENSIONS ARE IN MM.
 2) PAD ALLOY: Cu Post (50um Thick)
 3) PAD Cu DIAMETER: 0.15mm.
 4) DIE MATERIAL: Si (SILICON).
 5) DAISY CHAIN PATTERN (SEE PAGE 2).

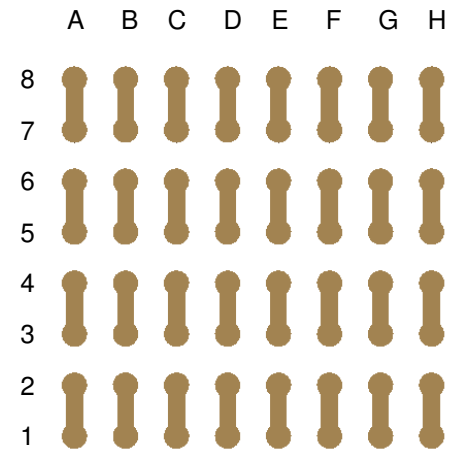
TOLERANCE UNLESS NOTED		APPROVALS	DATE	TopLine [®]			
X.X	+/- 0.3	DRAWN J. Hines	12/29/2010				
X.XX	+/- 0.03						
X.XXX	+/- 0.003	ENG		SCALE	SIZE	DRAWING NO.	REV
ALL DIMENSIONS IN		MFG		32.5:1	A	630880	A
INCHES <input type="checkbox"/> MILLIMETERS <input checked="" type="checkbox"/>		QA		DO NOT SCALE DRAWING			
THIRD ANGLE PROJECTION		CUST					
		REVISED					

DAISY CHAIN PATTERN

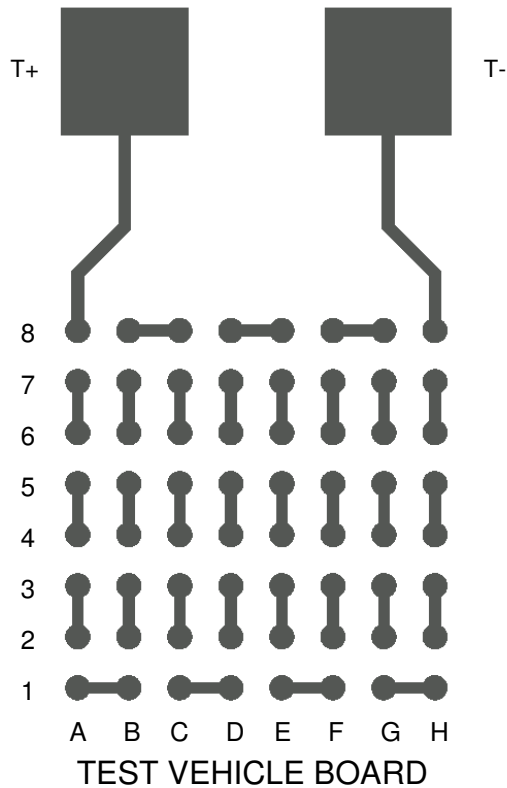
PAD VIEW



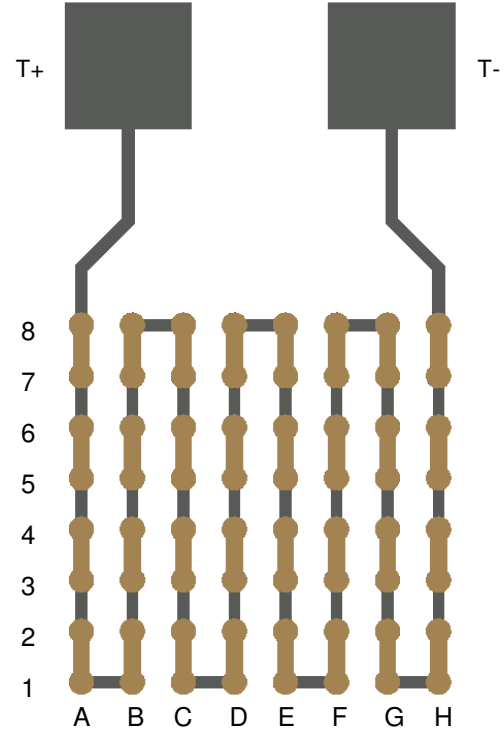
BOTTOM SIDE
(TOP X-RAY VIEW)



TOP VIEW



AFTER MOUNTING
TO TEST BOARD
(TOP X-RAY VIEW)



Notes:

- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.

TopLine ®			
TITLE eWLP64T.3C-DC088D 64-L P=0.3mm (TEG0306)			
SCALE 22.5:1	SIZE A	DRAWING NO. 630880	REV A
DO NOT SCALE DRAWING		SHEET 2 OF 2	